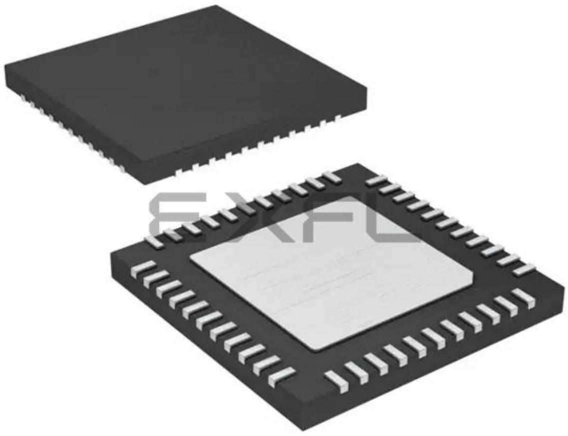

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What is "Embedded - Microcontrollers"?

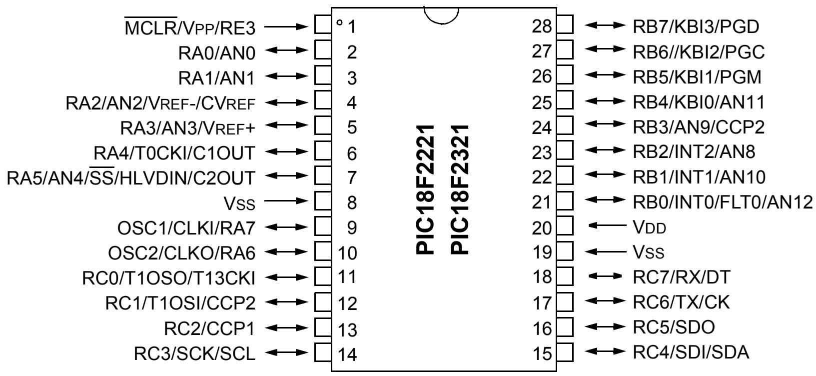
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

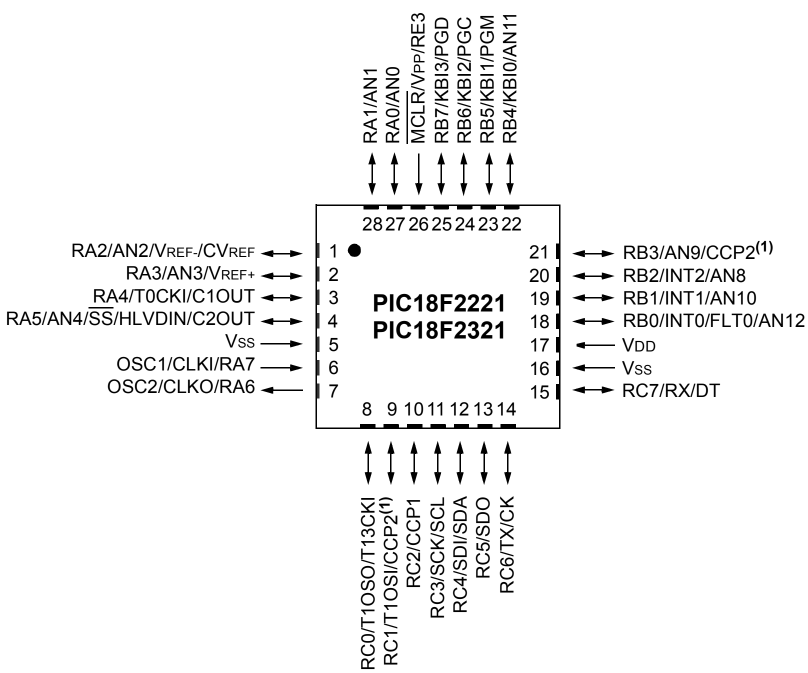
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf4221t-i-ml

Pin Diagrams

28-Pin SPDIP, SOIC, SSOP



28-Pin QFN



Note 1: RB3 is the alternate pin for CCP2 multiplexing.

TABLE 1-3: PIC18F4221/4321 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	15	34	32			
RC0				I/O	ST	Digital I/O.
T1OSO				O	—	Timer1 oscillator analog output.
T13CKI				I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2	16	35	35			
RC1				I/O	ST	Digital I/O.
T1OSI				I	CMOS	Timer1 oscillator analog input.
CCP2(1)				I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
RC2/CCP1/P1A	17	36	36			
RC2				I/O	ST	Digital I/O.
CCP1				I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
P1A				O	—	Enhanced CCP1 output.
RC3/SCK/SCL	18	37	37			
RC3				I/O	ST	Digital I/O.
SCK				I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL				I/O	I^2C	Synchronous serial clock input/output for I^2C™ mode.
RC4/SDI/SDA	23	42	42			
RC4				I/O	ST	Digital I/O.
SDI				I	ST	SPI data in.
SDA				I/O	I^2C	I^2C data I/O.
RC5/SDO	24	43	43			
RC5				I/O	ST	Digital I/O.
SDO				O	—	SPI data out.
RC6/TX/CK	25	44	44			
RC6				I/O	ST	Digital I/O.
TX				O	—	EUSART asynchronous transmit.
CK				I/O	ST	EUSART synchronous clock (see related RX/DT).
RC7/RX/DT	26	1	1			
RC7				I/O	ST	Digital I/O.
RX				I	ST	EUSART asynchronous receive.
DT				I/O	ST	EUSART synchronous data (see related TX/CK).

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels; I = Input; P = Power
I^2C = ST with I^2C™ or SMB levels; O = Output

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F4221/4321 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTE is a bidirectional I/O port.
RE0/$\overline{RD}$/AN5	8	25	25			
RE0				I/O	ST	Digital I/O.
$\overline{RD}$				I	TTL	Read control for Parallel Slave Port (see also $\overline{WR}$ and $\overline{CS}$ pins).
AN5				I	Analog	Analog Input 5.
RE1/$\overline{WR}$/AN6	9	26	26			
RE1				I/O	ST	Digital I/O.
$\overline{WR}$				I	TTL	Write control for Parallel Slave Port (see $\overline{CS}$ and $\overline{RD}$ pins).
AN6				I	Analog	Analog Input 6.
RE2/$\overline{CS}$/AN7	10	27	27			
RE2				I/O	ST	Digital I/O.
$\overline{CS}$				I	TTL	Chip Select control for Parallel Slave Port (see related $\overline{RD}$ and $\overline{WR}$).
AN7				I	Analog	Analog Input 7.
RE3	—	—	—	—	—	See $\overline{MCLR}$/VPP/RE3 pin.
VSS	12, 31	6, 30, 31	6, 29	P	—	Ground reference for logic and I/O pins.
VDD	11, 32	7, 8, 28, 29	7, 28	P	—	Positive supply for logic and I/O pins.
NC	—	13	12, 13, 33, 34	—	—	No Connect.

Legend: TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C = ST with I^2C™ or SMB levels; CMOS = CMOS compatible input or output; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 3-2: CAPACITOR SELECTION FOR QUARTZ CRYSTALS

Osc Type	Crystal Freq	Typical Capacitor Values Tested:	
		C1	C2
LP	32 kHz	22 pF	22 pF
XT	1 MHz 4 MHz	22 pF 22 pF	22 pF 22 pF
HS	4 MHz 10 MHz 20 MHz 25 MHz	22 pF 22 pF 22 pF 22 pF	22 pF 22 pF 22 pF 22 pF

Capacitor values are for design guidance only.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected V_{DD} and temperature range for the application. Refer to the following application notes for oscillator specific information:

- *AN588, "PIC® Microcontroller Oscillator Design Guide"*
- *AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices"*
- *AN849, "Basic PIC® Oscillator Design"*
- *AN943, "Practical PIC® Oscillator Analysis and Design"*
- AN949, "Making Your Oscillator Work"

See the notes following this table for additional information.

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

2: When operating below 3V V_{DD}, or when using certain ceramic resonators at any voltage, it may be necessary to use the HS mode or switch to a crystal oscillator.

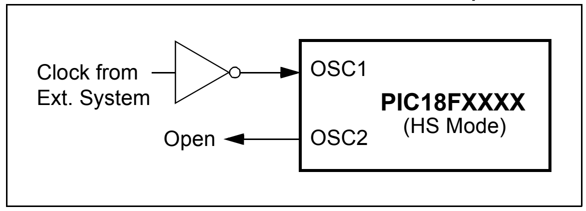
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: R_S may be required to avoid overdriving crystals with low drive level specification.

5: Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.

An external clock source may also be connected to the OSC1 pin in the HS mode, as shown in Figure 3-2. When operated in this mode, parameters D033 and D043 apply.

FIGURE 3-2: EXTERNAL CLOCK INPUT OPERATION (HS OSC CONFIGURATION)

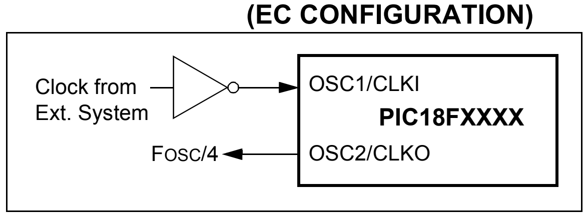


3.3 External Clock Input

The EC and ECIO Oscillator modes require an external clock source to be connected to the OSC1 pin. There is no oscillator start-up time required after a Power-on Reset or after an exit from Sleep mode.

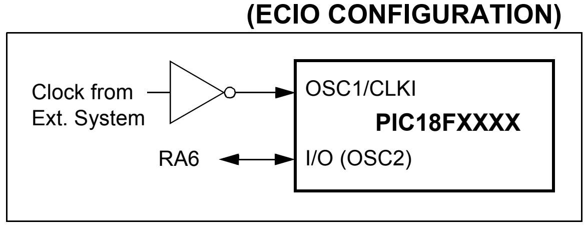
In the EC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 3-3 shows the pin connections for the EC Oscillator mode.

FIGURE 3-3: EXTERNAL CLOCK INPUT OPERATION (EC CONFIGURATION)



The ECIO Oscillator mode functions like the EC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 3-4 shows the pin connections for the ECIO Oscillator mode. When operated in this mode, parameters D033A and D043A apply.

FIGURE 3-4: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



3.6 Internal Oscillator Block

The PIC18F2221/2321/4221/4321 family of devices includes an internal oscillator block which generates two different clock signals; either can be used as the microcontroller’s clock source. This may eliminate the need for external oscillator circuits on the OSC1 and/or OSC2 pins.

The main output (INTOSC) is an 8 MHz clock source, which can be used to directly drive the device clock. It also drives a postscaler, which can provide a range of clock frequencies from 31 kHz to 4 MHz. The INTOSC output is enabled when a clock frequency from 125 kHz to 8 MHz is selected. The INTOSC output can also be enabled when 31 kHz is selected, depending on the INTSRC bit (OSCTUNE<7>).

The other clock source is the internal RC oscillator (INTRC), which provides a nominal 31 kHz output. INTRC is enabled if it is selected as the device clock source; it is also enabled automatically when any of the following are enabled:

- Power-up Timer
- Fail-Safe Clock Monitor
- Watchdog Timer
- Two-Speed Start-up

These features are discussed in greater detail in **Section 24.0 “Special Features of the CPU”**.

The clock source frequency (INTOSC direct, INTRC direct or INTOSC postscaler) is selected by configuring the IRCF bits of the OSCCON register (page 37).

3.6.1 INTIO MODES

Using the internal oscillator as the clock source eliminates the need for up to two external oscillator pins, which can then be used for digital I/O. Two distinct configurations are available:

- In INTIO1 mode, the OSC2 pin outputs FOSC/4, while OSC1 functions as RA7 (see Figure 3-8) for digital input and output.
- In INTIO2 mode, OSC1 functions as RA7 and OSC2 functions as RA6 (see Figure 3-9), both for digital input and output.

FIGURE 3-8: INTIO1 OSCILLATOR MODE

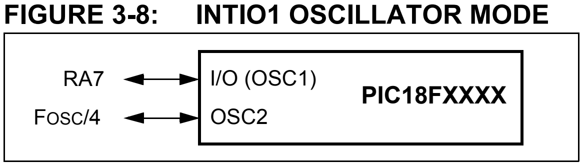
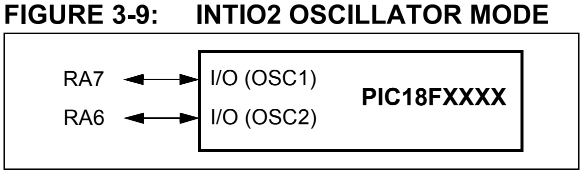


FIGURE 3-9: INTIO2 OSCILLATOR MODE



3.6.2 INTOSC OUTPUT FREQUENCY

The internal oscillator block is calibrated at the factory to produce an INTOSC output frequency of 8 MHz.

The INTRC oscillator operates independently of the INTOSC source. Any changes in INTOSC across voltage and temperature are not necessarily reflected by changes in INTRC or vice versa.

3.6.3 OSCTUNE REGISTER

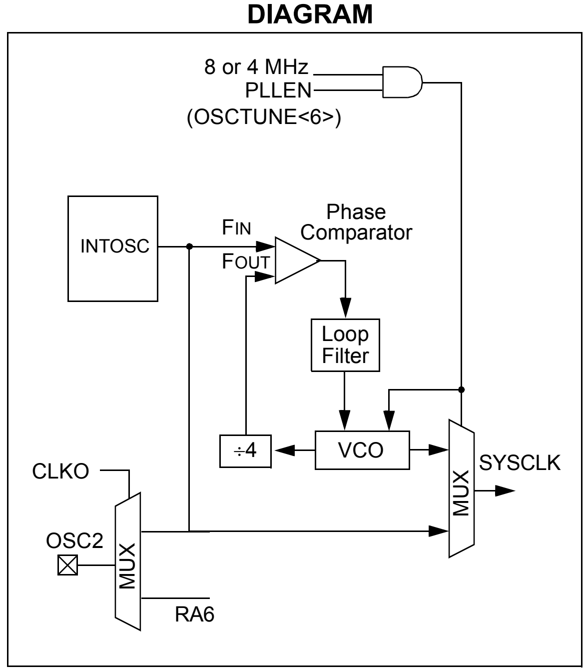
The INTOSC output has been calibrated at the factory but can be adjusted in the user’s application. This is done by writing to TUN<4:0> (OSCTUNE<4:0>) in the OSCTUNE register (Register 3-1).

When the OSCTUNE register is modified, the INTOSC frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred. The INTRC is not affected by OSCTUNE.

The OSCTUNE register also implements the INTSRC (OSCTUNE<7>) and PLLEN (OSCTUNE<6>) bits, which control certain features of the internal oscillator block. The INTSRC bit allows users to select which internal oscillator provides the clock source when the 31 kHz frequency option is selected. This is covered in greater detail in **Section 3.7.1 “Oscillator Control Register”**.

The PLLEN bit controls the operation of the Phase Locked Loop (PLL) in Internal Oscillator modes (see Figure 3-10).

FIGURE 3-10: INTOSC AND PLL BLOCK DIAGRAM



8.5 Operation During Code-Protect

Data EEPROM memory has its own code-protect bits in Configuration Words. External read and write operations are disabled if code protection is enabled.

The microcontroller itself can both read and write to the internal data EEPROM, regardless of the state of the code-protect Configuration bit. Refer to **Section 24.0 "Special Features of the CPU"** for additional information.

8.6 Protection Against Spurious Write

To protect against spurious EEPROM writes, various mechanisms have been implemented. On power-up, the WREN bit is cleared. In addition, writes to the EEPROM are blocked during the Power-up Timer period (T_{PWRT}, parameter 33).

The write initiate sequence and the WREN bit together help prevent an accidental write during Brown-out Reset, power glitch or software malfunction.

8.7 Using the Data EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing data. Such data is typically updated at least one time within the number of writes defined by specification, D124. If any location storing data is not written at least this often, the data EEPROM array must be refreshed. For this reason, values that change infrequently, or not at all, should be stored in Flash program memory.

A simple data EEPROM refresh routine is shown in Example 8-3.

Note:	If data EEPROM is only used to store constants and/or data that changes often, an array refresh is likely not required. See specification, D124.

EXAMPLE 8-3: DATA EEPROM REFRESH ROUTINE

```
        CLRF    EEADR           ; Start at address 0
        BCF     EECON1, CFGS    ; Set for memory
        BCF     EECON1, EEPGD   ; Set for Data EEPROM
        BCF     INTCON, GIE     ; Disable interrupts
        BSF     EECON1, WREN    ; Enable writes
LOOP                            ; Loop to refresh array
        BSF     EECON1, RD      ; Read current address
        MOVLW   55h             ;
        MOVWF   EECON2          ; Write 55h
        MOVLW   0AAh            ;
        MOVWF   EECON2          ; Write 0AAh
        BSF     EECON1, WR      ; Set WR bit to begin write
        BTFSC   EECON1, WR      ; Wait for write to complete
        BRA     $-2
        INCFSZ  EEADR, F        ; Increment address
        BRA     LOOP            ; Not zero, do it again

        BCF     EECON1, WREN    ; Disable writes
        BSF     INTCON, GIE     ; Enable interrupts
```


TABLE 11-7: PORTD I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RD0/PSP0	RD0	0	O	DIG	LATD<0> data output.
		1	I	ST	PORTD<0> data input.
	PSP0	x	O	DIG	PSP read data output (LATD<0>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD1/PSP1	RD1	0	O	DIG	LATD<1> data output.
		1	I	ST	PORTD<1> data input.
	PSP1	x	O	DIG	PSP read data output (LATD<1>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD2/PSP2	RD2	0	O	DIG	LATD<2> data output.
		1	I	ST	PORTD<2> data input.
	PSP2	x	O	DIG	PSP read data output (LATD<2>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD3/PSP3	RD3	0	O	DIG	LATD<3> data output.
		1	I	ST	PORTD<3> data input.
	PSP3	x	O	DIG	PSP read data output (LATD<3>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD4/PSP4	RD4	0	O	DIG	LATD<4> data output.
		1	I	ST	PORTD<4> data input.
	PSP4	x	O	DIG	PSP read data output (LATD<4>); takes priority over port data.
		x	I	TTL	PSP write data input.
RD5/PSP5/P1B	RD5	0	O	DIG	LATD<5> data output.
		1	I	ST	PORTD<5> data input.
	PSP5	x	O	DIG	PSP read data output (LATD<5>); takes priority over port data.
		x	I	TTL	PSP write data input.
	P1B	0	O	DIG	ECCP1 Enhanced PWM output, Channel B; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RD6/PSP6/P1C	RD6	0	O	DIG	LATD<6> data output.
		1	I	ST	PORTD<6> data input.
	PSP6	x	O	DIG	PSP read data output (LATD<6>); takes priority over port data.
		x	I	TTL	PSP write data input.
	P1C	0	O	DIG	ECCP1 Enhanced PWM output, channel C; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.
RD7/PSP7/P1D	RD7	0	O	DIG	LATD<7> data output.
		1	I	ST	PORTD<7> data input.
	PSP7	x	O	DIG	PSP read data output (LATD<7>); takes priority over port data.
		x	I	TTL	PSP write data input.
	P1D	0	O	DIG	ECCP1 Enhanced PWM output, Channel D; takes priority over port and PSP data. May be configured for tri-state during Enhanced PWM shutdown events.

Legend: DIG = Digital level output; TTL = TTL input buffer; ST = Schmitt Trigger input buffer; x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

14.2 Timer2 Interrupt

Timer2 can also generate an optional device interrupt. The Timer2 output signal (TMR2 to PR2 match) provides the input for the 4-bit output counter/postscaler. This counter generates the TMR2 match interrupt flag which is latched in TMR2IF (PIR1<1>). The interrupt is enabled by setting the TMR2 Match Interrupt Enable bit, TMR2IE (PIE1<1>).

A range of 16 postscale options (from 1:1 through 1:16 inclusive) can be selected with the postscaler control bits, T2OUTPS<3:0> (T2CON<6:3>).

14.3 Timer2 Output

The unscaled output of TMR2 is available primarily to the CCP modules, where it is used as a time base for operations in PWM mode.

Timer2 can be optionally used as the shift clock source for the MSSP module operating in SPI mode. Additional information is provided in **Section 18.0 "Master Synchronous Serial Port (MSSP) Module"**.

FIGURE 14-1: TIMER2 BLOCK DIAGRAM

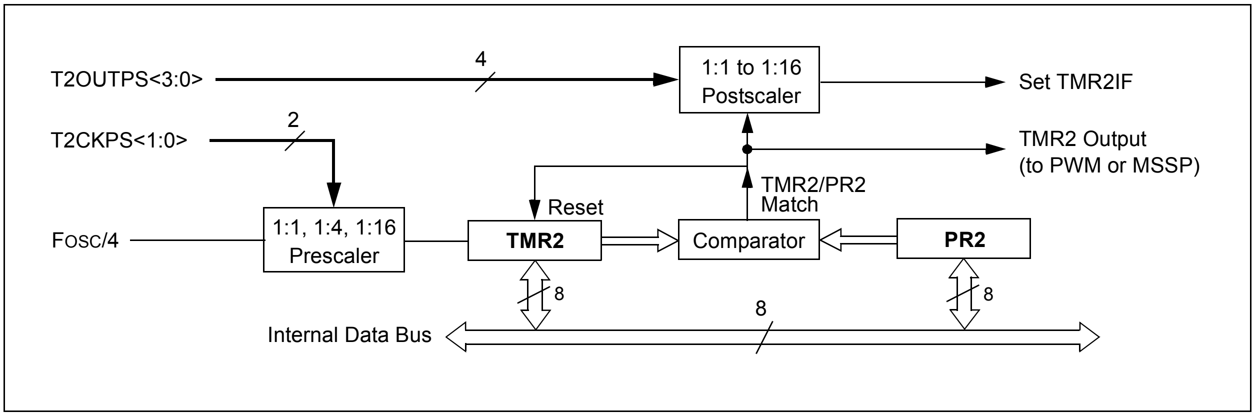


TABLE 14-1: REGISTERS ASSOCIATED WITH TIMER2 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	55
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	58
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	58
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	58
TMR2	Timer2 Register								56
T2CON	—	T2OUTPS3	T2OUTPS2	T2OUTPS1	T2OUTPS0	TMR2ON	T2CKPS1	T2CKPS0	56
PR2	Timer2 Period Register								56

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Timer2 module.

Note 1: These bits are unimplemented on 28-pin devices and read as '0'.

FIGURE 18-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

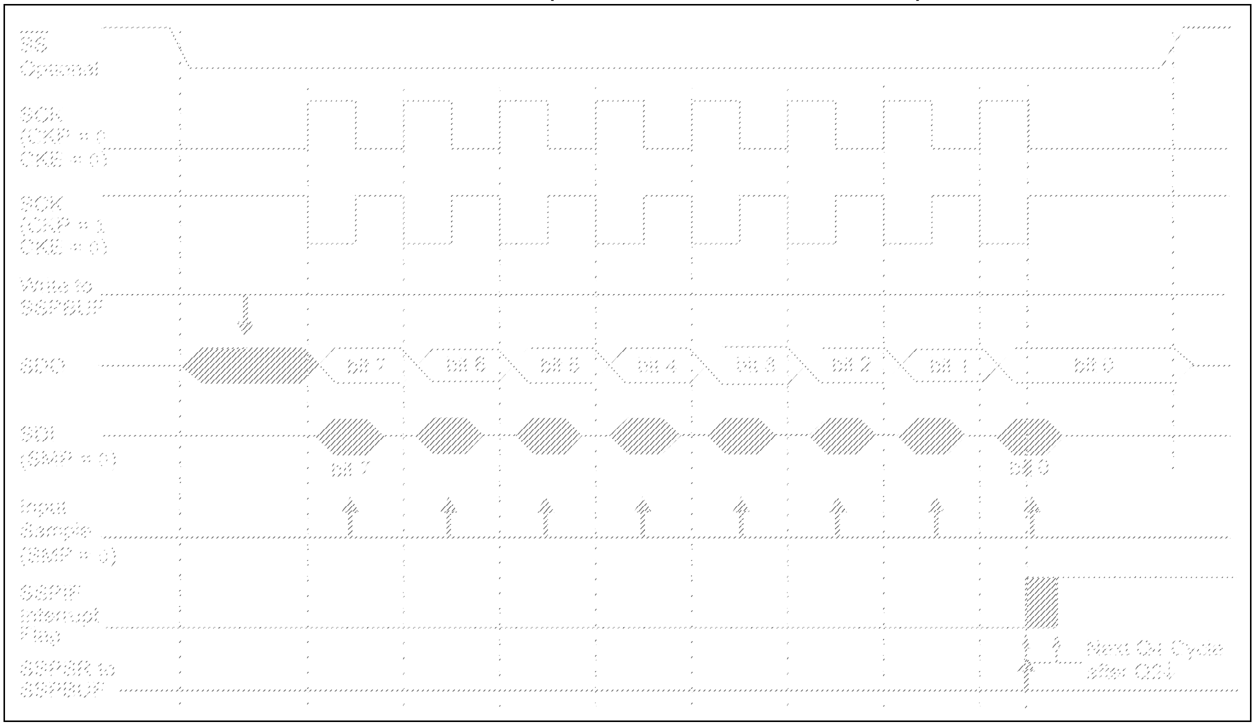
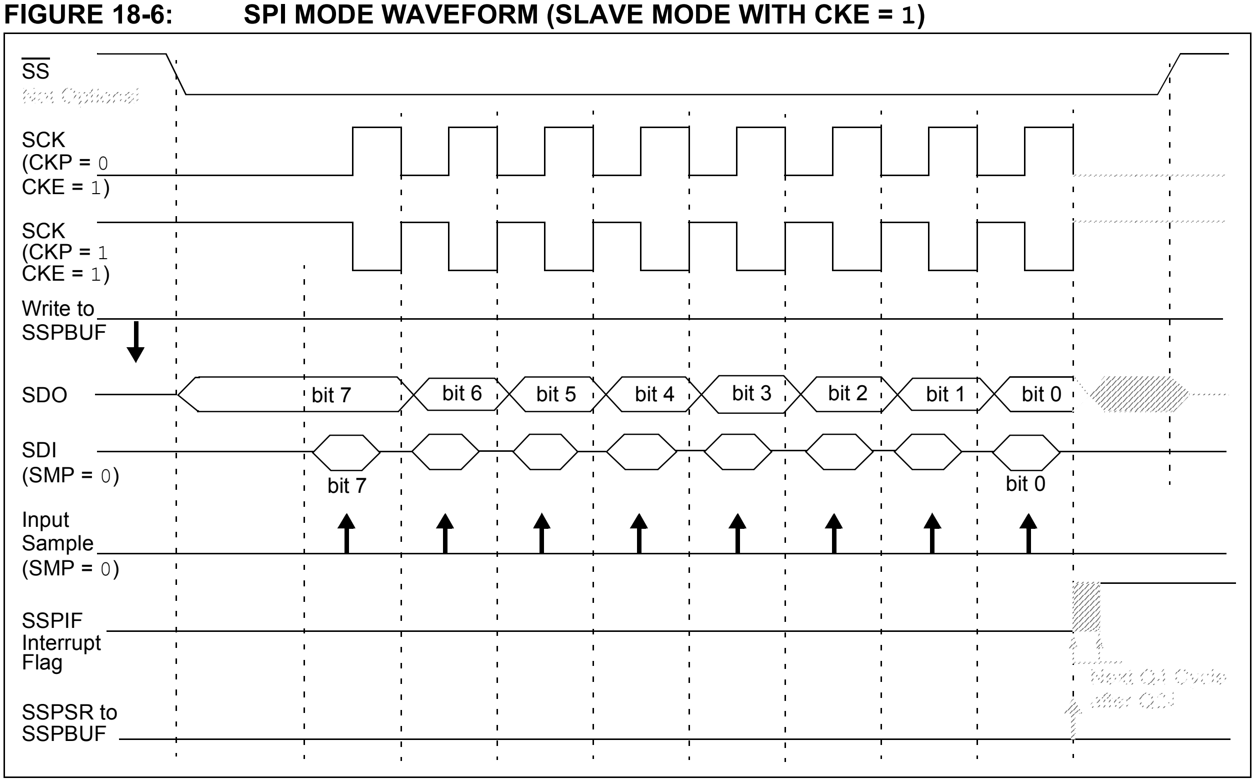


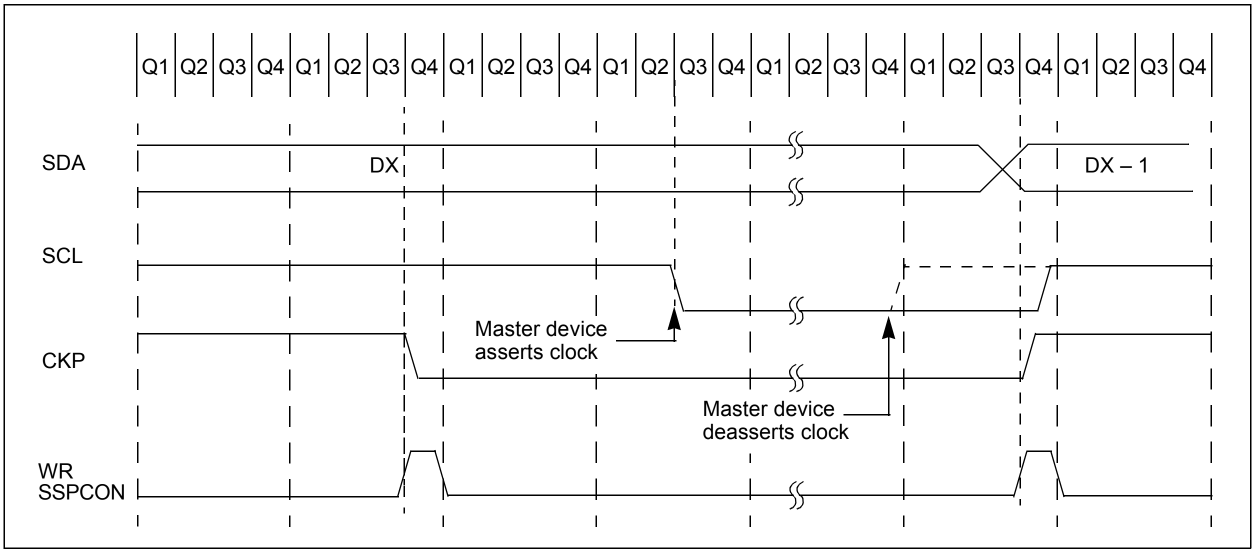
FIGURE 18-6: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



18.4.4.5 Clock Synchronization and the CKP bit

When the CKP bit is cleared, the SCL output is forced to '0'. However, clearing the CKP bit will not assert the SCL output low until the SCL output is already sampled low. Therefore, the CKP bit will not assert the SCL line until an external I²C master device has already asserted the SCL line. The SCL output will remain low until the CKP bit is set and all other devices on the I²C bus have deasserted SCL. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCL (see Figure 18-14).

FIGURE 18-14: CLOCK SYNCHRONIZATION TIMING



18.4.6 MASTER MODE

Master mode is enabled by setting and clearing the appropriate SSPM bits in SSPCON1 and by setting the SSPEN bit. In Master mode, the SCL and SDA lines are manipulated by the MSSP hardware.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I^{2}C bus may be taken when the P bit is set, or the bus is Idle, with both the S and P bits clear.

In Firmware Controlled Master mode, user code conducts all I^{2}C bus operations based on Start and Stop bit conditions.

Once Master mode is enabled, the user has six options.

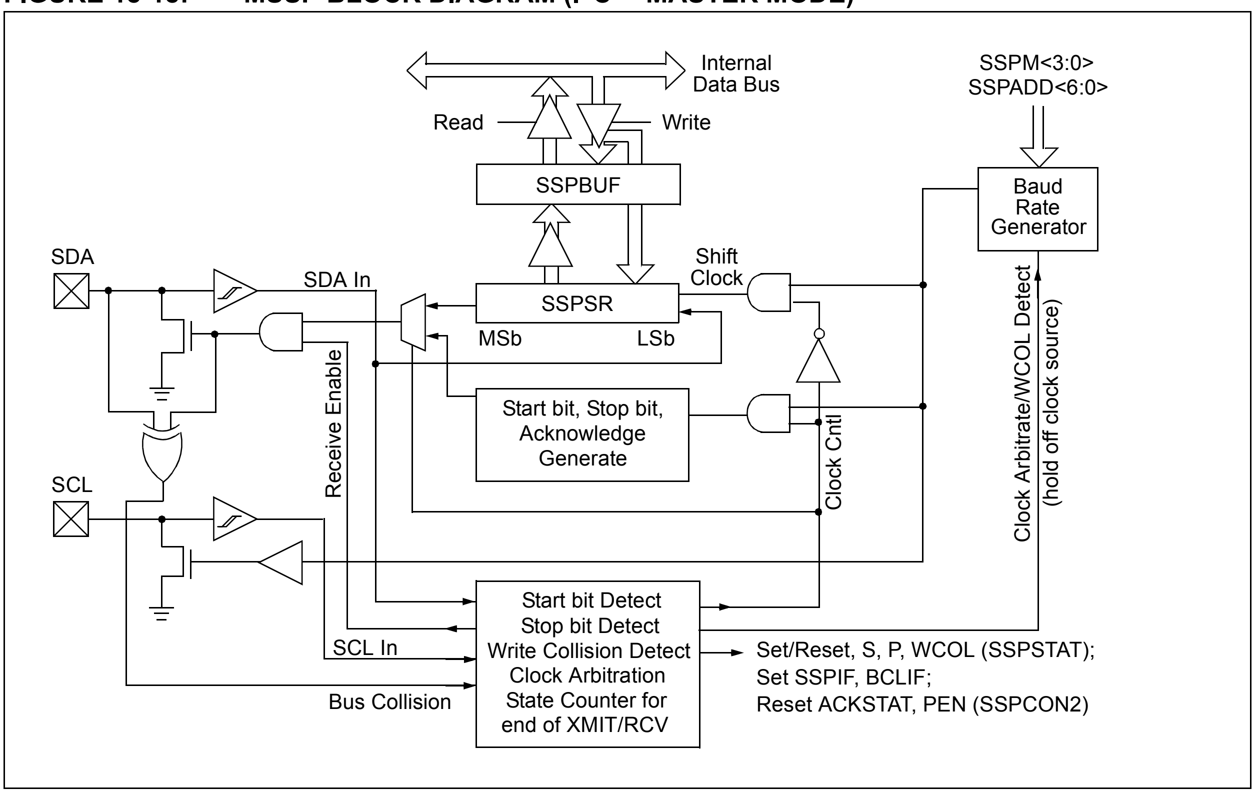
1. Assert a Start condition on SDA and SCL.
2. Assert a Repeated Start condition on SDA and SCL.
3. Write to the SSPBUF register initiating transmission of data/address.
4. Configure the I^{2}C port to receive data.
5. Generate an Acknowledge condition at the end of a received byte of data.
6. Generate a Stop condition on SDA and SCL.

Note: The MSSP module, when configured in I^{2}C Master mode, does not allow queueing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPBUF register to initiate transmission before the Start condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur.

The following events will cause the MSSP Interrupt Flag bit, SSPIF, to be set (MSSP interrupt, if enabled):

- Start condition
- Stop condition
- Data transfer byte transmitted/received
- Acknowledge transmit
- Repeated Start

FIGURE 18-18: MSSP BLOCK DIAGRAM (I^{2}C™ MASTER MODE)



18.4.10 I²C MASTER MODE TRANSMISSION

Transmission of a data byte, a 7-bit address or the other half of a 10-bit address is accomplished by simply writing a value to the SSPBUF register. This action will set the Buffer Full flag bit, BF and allow the Baud Rate Generator to begin counting and start the next transmission. Each bit of address/data will be shifted out onto the SDA pin after the falling edge of SCL is asserted (see data hold time specification parameter 106). SCL is held low for one Baud Rate Generator rollover count (TBRG). Data should be valid before SCL is released high (see data setup time specification parameter 107). When the SCL pin is released high, it is held that way for TBRG. The data on the SDA pin must remain stable for that duration and some hold time after the next falling edge of SCL. After the eighth bit is shifted out (the falling edge of the eighth clock), the BF flag is cleared and the master releases SDA. This allows the slave device being addressed to respond with an $\overline{\text{ACK}}$ bit during the ninth bit time if an address match occurred, or if data was received properly. The status of $\overline{\text{ACK}}$ is written into the ACKDT bit on the falling edge of the ninth clock. If the master receives an Acknowledge, the Acknowledge Status bit, ACKSTAT, is cleared. If not, the bit is set. After the ninth clock, the SSPIF bit is set and the master clock (Baud Rate Generator) is suspended until the next data byte is loaded into the SSPBUF, leaving SCL low and SDA unchanged (Figure 18-23).

After the write to the SSPBUF, each bit of the address will be shifted out on the falling edge of SCL until all seven address bits and the R/$\overline{\text{W}}$ bit are completed. On the falling edge of the eighth clock, the master will deassert the SDA pin, allowing the slave to respond with an Acknowledge. On the falling edge of the ninth clock, the master will sample the SDA pin to see if the address was recognized by a slave. The status of the $\overline{\text{ACK}}$ bit is loaded into the ACKSTAT status bit (SSPCON2<6>). Following the falling edge of the ninth clock transmission of the address, the SSPIF is set, the BF flag is cleared and the Baud Rate Generator is turned off until another write to the SSPBUF takes place, holding SCL low and allowing SDA to float.

18.4.10.1 BF Status Flag

In Transmit mode, the BF bit (SSPSTAT<0>) is set when the CPU writes to SSPBUF and is cleared when all 8 bits are shifted out.

18.4.10.2 WCOL Status Flag

If the user writes the SSPBUF when a transmit is already in progress (i.e., SSPSR is still shifting out a data byte), the WCOL flag is set and the contents of the buffer are unchanged (the write doesn't occur) after 2 TCY after the SSPBUF write. If SSPBUF is rewritten within 2 TCY, the WCOL bit is set and SSPBUF is updated. This may result in a corrupted transfer. The user should verify that the WCOL flag is clear after each write to SSPBUF to ensure the transfer is correct.

18.4.10.3 ACKSTAT Status Flag

In Transmit mode, the ACKSTAT bit (SSPCON2<6>) is cleared when the slave has sent an Acknowledge ($\overline{\text{ACK}}$ = 0) and is set when the slave does not Acknowledge ($\overline{\text{ACK}}$ = 1). A slave sends an Acknowledge when it has recognized its address (including a general call), or when the slave has properly received its data.

18.4.11 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the Receive Enable bit, RCEN (SSPCON2<3>).

Note:	The MSSP module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCL pin changes (high-to-low/low-to-high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag bit is set, the SSPIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCL low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable bit, ACKEN (SSPCON2<4>).

18.4.11.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when the SSPBUF register is read.

18.4.11.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when 8 bits are received into the SSPSR and the BF flag bit is already set from a previous reception.

18.4.11.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write doesn't occur).

TABLE 19-3: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	8332	0.300	0.02	4165	0.300	0.02	2082	0.300	-0.04	1665
1.2	1.200	0.02	2082	1.200	-0.03	1041	1.200	-0.03	520	1.201	-0.16	415
2.4	2.402	0.06	1040	2.399	-0.03	520	2.404	0.16	259	2.403	-0.16	207
9.6	9.615	0.16	259	9.615	0.16	129	9.615	0.16	64	9.615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19.230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55.555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.04	832	0.300	-0.16	415	0.300	-0.16	207
1.2	1.202	0.16	207	1.201	-0.16	103	1.201	-0.16	51
2.4	2.404	0.16	103	2.403	-0.16	51	2.403	-0.16	25
9.6	9.615	0.16	25	9.615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	33332	0.300	0.00	16665	0.300	0.00	8332	0.300	-0.01	6665
1.2	1.200	0.00	8332	1.200	0.02	4165	1.200	0.02	2082	1.200	-0.04	1665
2.4	2.400	0.02	4165	2.400	0.02	2082	2.402	0.06	1040	2.400	-0.04	832
9.6	9.606	0.06	1040	9.596	-0.03	520	9.615	0.16	259	9.615	-0.16	207
19.2	19.193	-0.03	520	19.231	0.16	259	19.231	0.16	129	19.230	-0.16	103
57.6	57.803	0.35	172	57.471	-0.22	86	58.140	0.94	42	57.142	0.79	34
115.2	114.943	-0.22	86	116.279	0.94	42	113.636	-1.36	21	117.647	-2.12	16

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.01	3332	0.300	-0.04	1665	0.300	-0.04	832
1.2	1.200	0.04	832	1.201	-0.16	415	1.201	-0.16	207
2.4	2.404	0.16	415	2.403	-0.16	207	2.403	-0.16	103
9.6	9.615	0.16	103	9.615	-0.16	51	9.615	-0.16	25
19.2	19.231	0.16	51	19.230	-0.16	25	19.230	-0.16	12
57.6	58.824	2.12	16	55.555	3.55	8	—	—	—
115.2	111.111	-3.55	8	—	—	—	—	—	—

20.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/$\overline{\text{DONE}}$ bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provides a range of 2 to 20 TAD. When the GO/$\overline{\text{DONE}}$ bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/$\overline{\text{DONE}}$ bit.

Manual acquisition is selected when ACQT<2:0> = `000`. When the GO/$\overline{\text{DONE}}$ bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/$\overline{\text{DONE}}$ bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/$\overline{\text{DONE}}$ bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

20.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 11 TAD per 10-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (see parameter 130 for more information).

Table 20-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 20-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Maximum Device Frequency	
Operation	**ADCS<2:0>**	**PIC18F2X21/4X21**	**PIC18LF2X21/4X21(4)**
2 TOSC	`000`	2.86 MHz	1.43 kHz
4 TOSC	`100`	5.71 MHz	2.86 MHz
8 TOSC	`001`	11.43 MHz	5.72 MHz
16 TOSC	`101`	22.86 MHz	11.43 MHz
32 TOSC	`010`	40.0 MHz	22.86 MHz
64 TOSC	`110`	40.0 MHz	22.86 MHz
RC(3)	`x11`	1.00 MHz(1)	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 1.2 μs.
2: The RC source has a typical TAD time of 2.5 μs.
3: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or the A/D accuracy may be out of specification.
4: Low-power (PIC18LFXXXX) devices only.

REGISTER 24-1: CONFIG1H: CONFIGURATION REGISTER 1 HIGH (BYTE ADDRESS 300001h)

R/P-0	R/P-0	U-0	U-0	R/P-0	R/P-1	R/P-1	R/P-1
IESO	FCMEN	—	—	FOSC3	FOSC2	FOSC1	FOSC0
bit 7							bit 0

bit 7 **IESO:** Internal/External Oscillator Switchover bit
1 = Oscillator Switchover mode enabled
0 = Oscillator Switchover mode disabled

bit 6 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor enabled
0 = Fail-Safe Clock Monitor disabled

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **FOSC<3:0>:** Oscillator Selection bits
11xx = External RC oscillator, CLKO function on RA6
101x = External RC oscillator, CLKO function on RA6
1001 = Internal oscillator block, CLKO function on RA6, port function on RA7
1000 = Internal oscillator block, port function on RA6 and RA7
0111 = External RC oscillator, port function on RA6
0110 = HS oscillator, PLL enabled (Clock Frequency = 4 x FOSC1)
0101 = EC oscillator, port function on RA6
0100 = EC oscillator, CLKO function on RA6
0011 = External RC oscillator, CLKO function on RA6
0010 = HS oscillator
0001 = XT oscillator
0000 = LP oscillator

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

24.3 Two-Speed Start-up

The Two-Speed Start-up feature helps to minimize the latency period from oscillator start-up to code execution by allowing the microcontroller to use the INTOSC oscillator as a clock source until the primary clock source is available. It is enabled by setting the IESO Configuration bit.

Two-Speed Start-up should be enabled only if the primary oscillator mode is LP, XT, HS or HSPLL (crystal-based modes). Other sources do not require an OST start-up delay; for these, Two-Speed Start-up should be disabled.

When enabled, Resets and wake-ups from Sleep mode cause the device to configure itself to run from the internal oscillator block as the clock source, following the time-out of the Power-up Timer after a Power-on Reset is enabled. This allows almost immediate code execution while the primary oscillator starts and the OST is running. Once the OST times out, the device automatically switches to PRI_RUN mode.

To use a higher clock speed on wake-up, the INTOSC or postscaler clock sources can be selected to provide a higher clock speed by setting bits, IRCF<2:0>, immediately after Reset. For wake-ups from Sleep, the INTOSC or postscaler clock sources can be selected by setting the IRCF<2:0> bits prior to entering Sleep mode.

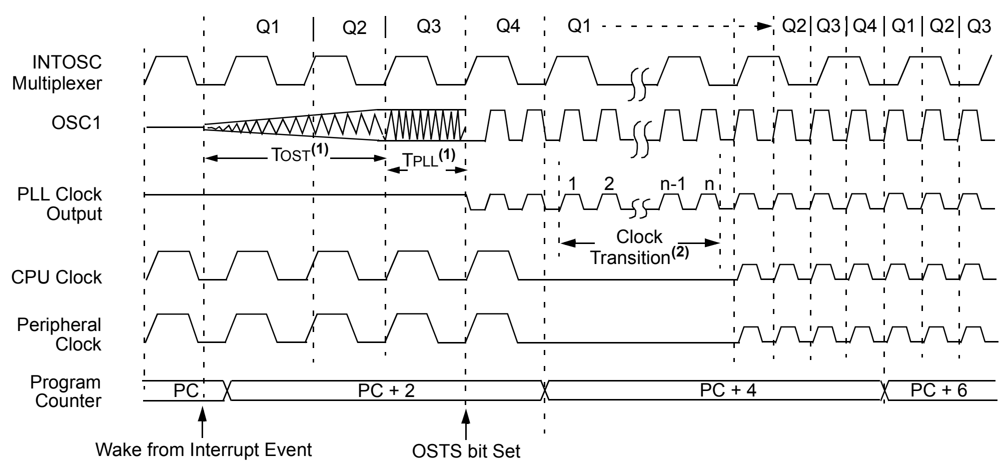
In all other power-managed modes, Two-Speed Start-up is not used. The device will be clocked by the currently selected clock source until the primary clock source becomes available. The setting of the IESO bit is ignored.

24.3.1 SPECIAL CONSIDERATIONS FOR USING TWO-SPEED START-UP

While using the INTOSC oscillator in Two-Speed Start-up, the device still obeys the normal command sequences for entering power-managed modes, including multiple `SLEEP` instructions (refer to **Section 4.1.4 "Multiple Sleep Commands"**). In practice, this means that user code can change the SCS<1:0> bit settings or issue `SLEEP` instructions before the OST times out. This would allow an application to briefly wake-up, perform routine "housekeeping" tasks and return to Sleep before the device starts to operate from the primary oscillator.

User code can also check if the primary clock source is currently providing the device clocking by checking the status of the OSTS bit (OSCCON<3>). If the bit is set, the primary oscillator is providing the clock. Otherwise, the internal oscillator block is providing the clock during wake-up from Reset or Sleep mode.

FIGURE 24-2: TIMING TRANSITION FOR TWO-SPEED START-UP (INTOSC TO HSPLL)



Note 1: T_{OST} = 1024 T_{OSC}; T_{PLL} = 2 ms (approx). These intervals are not shown to scale.

2: Clock transition typically occurs within 2-4 T_{OSC}.

NEGF	Negate f			
Syntax:	NEGF f {,a}			
Operands:	$0 \le f \le 255$ a ∈ [0,1]			
Operation:	$(\bar{f}) + 1 \rightarrow f$			
Status Affected:	N, OV, C, DC, Z			
Encoding:	0110	110a	ffff	ffff
Description:	Location ‘f’ is negated using two’s complement. The result is placed in the data memory location ‘f’. If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank (default). If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.			
Words:	1			
Cycles:	1			

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write register ‘f’

Example: NEGF REG, 1

Before Instruction
REG = 0011 1010 [3Ah]
After Instruction
REG = 1100 0110 [C6h]

NOP	No Operation			
Syntax:	NOP			
Operands:	None			
Operation:	No operation			
Status Affected:	None			
Encoding:	0000 1111	0000 xxxx	0000 xxxx	0000 xxxx
Description:	No operation.			
Words:	1			
Cycles:	1			

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	No operation	No operation

Example:

None.

FIGURE 27-1: PIC18F2221/2321/4221/4321 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

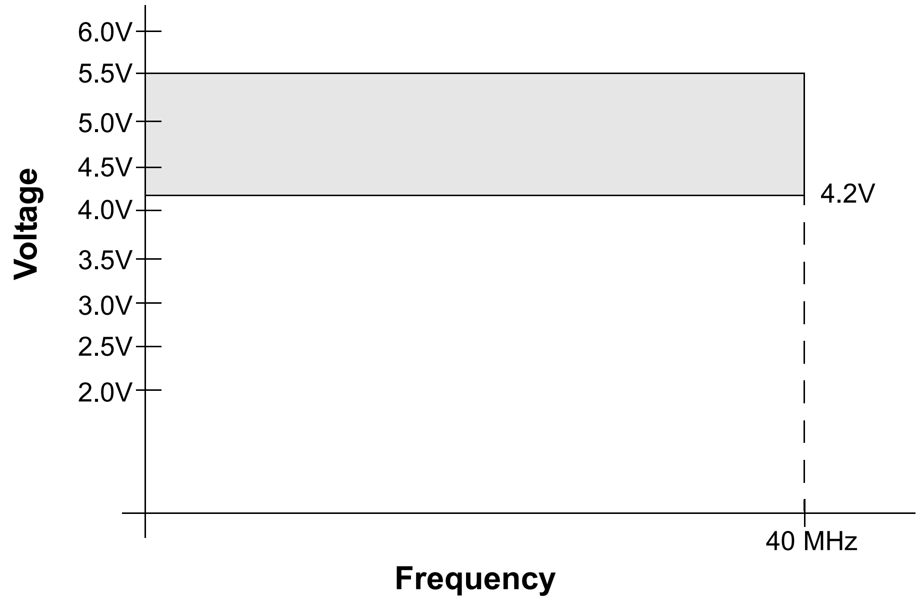
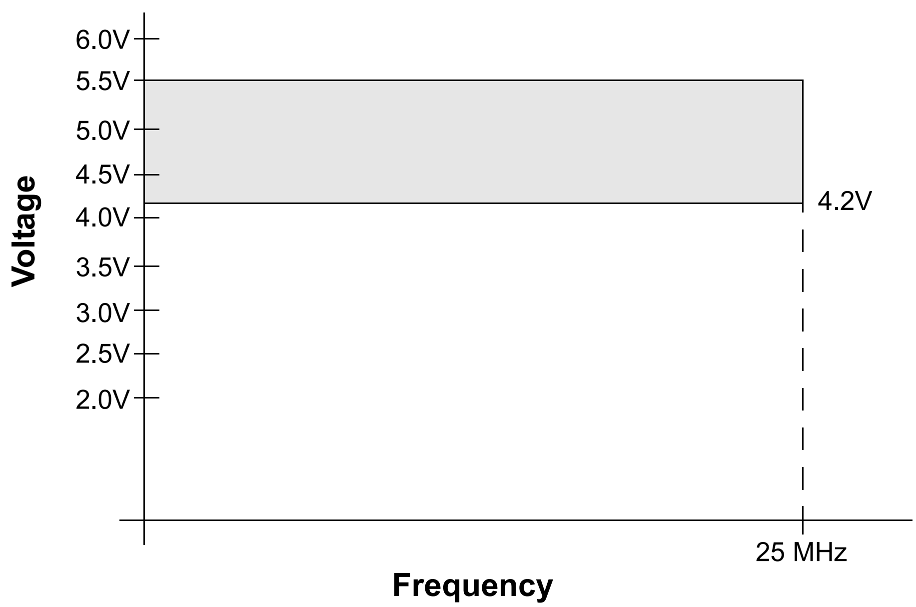


FIGURE 27-2: PIC18F2221/2321/4221/4321 VOLTAGE-FREQUENCY GRAPH (EXTENDED)



27.3 DC Characteristics: PIC18F2221/2321/4221/4321 (Industrial) PIC18LF2221/2321/4221/4321 (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended			
Param No.	Symbol	Characteristic	Min	Max	Units	Conditions
	VIL	**Input Low Voltage**				
		I/O Ports:				
D030		with TTL Buffer	VSS	0.15 VDD	V	VDD < 4.5V
D030A			—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D031		with Schmitt Trigger Buffer	VSS	0.2 VDD	V	
D031A		RC3 and RC4	VSS	0.3 VDD	V	I²C™ enabled
D031B			VSS	0.8	V	SMBus enabled
D032		$\overline{\text{MCLR}}$	VSS	0.2 VDD	V	
D033		OSC1	VSS	0.3 VDD	V	HS, HSPLL modes
D033A		OSC1	VSS	0.2 VDD	V	RC, EC modes(1)
D033B		OSC1	VSS	0.3	V	XT, LP modes
D034		T13CKI	VSS	0.3	V	
	VIH	**Input High Voltage**				
		I/O Ports:				
D040		with TTL Buffer	0.25 VDD + 0.8V	VDD	V	VDD < 4.5V
D040A			2.0	VDD	V	4.5V ≤ VDD ≤ 5.5V
D041		with Schmitt Trigger Buffer	0.8 VDD	VDD	V	
D041A		RC3 and RC4	0.7 VDD	VDD	V	I²C™ enabled
D041B			2.1	VDD	V	SMBus enabled, VSS ≥ 3V
D042		$\overline{\text{MCLR}}$	0.8 VDD	VDD	V	
D043		OSC1	0.7 VDD	VDD	V	HS, HSPLL modes
D043A		OSC1	0.8 VDD	VDD	V	EC mode
D043B		OSC1	0.9 VDD	VDD	V	RC mode(1)
D043C		OSC1	1.6	VDD	V	XT, LP modes
D044		T13CKI	1.6	VDD	V	
	IIL	**Input Leakage Current(2,3)**				
D060		I/O Ports	—	±200	nA	VDD < 5.5V, VSS ≤ VPIN ≤ VDD, Pin at High-Impedance
			—	±50	nA	VDD < 3V, VSS ≤ VPIN ≤ VDD, Pin at High-Impedance
D061		$\overline{\text{MCLR}}$	—	±1	μA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	±1	μA	Vss ≤ VPIN ≤ VDD

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

C

D